



**100% Material Declaration Data Sheet for  
FFV900**

PK776 (v1.0) Jan 22, 2016

FFV900

**Average Weight : 11.7917 g**

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight ( in grams)	Component % of total
Silicon die 1	Si	7440-21-3	100.00	basis	<b>0.388303</b>	<b>3.293%</b>
					0.388303	
Bump	Sn Ag	7440-31-5 7440-22-4	98.20 1.80	basis basis	<b>0.015339</b>	<b>0.130%</b>
					0.015063 0.000276	
Underfill	Bisphenol F type liquid epoxy resin 1,6-Bis(2,3-epoxypropoxy)naphthalene Bisphenol A type liquid epoxy resin  Amine type hardener Silicon dioxide Carbon black Additives	9003-36-5	15.00	basis	<b>0.049000</b>	<b>0.416%</b>
		27610-48-6	10.00	basis	0.007350	
		25068-38-6	5.00	basis	0.004900	
		trade secret	10.00	basis	0.002450	
		60676-86-0	58.00	filler	0.004900	
		1333-86-4	1.00	color agent	0.028420	
trade secret	1.00	additives	0.000490			
Solder paste	Sn Ag Cu	7440-31-5 7440-22-4 7440-50-8	96.50 3.00 0.50	metal metal metal	<b>0.005772</b>	<b>0.049%</b>
					0.005570 0.000173 0.000029	
Capacitor 1	BaTiO3 type Titanium dioxide Misc Ni Cu Silicon dioxide diboron trioxide; boric oxide Ni Sn	1304-28-5	40.00	Ceramic	<b>0.002400</b>	<b>0.020%</b>
		13463-67-7	20.00		0.000960	
		-	6.67	Inner electrode	0.000480	
		7440-02-0	2.42		0.000160	
		7440-50-8	20.73	Outer electrode	0.000058	
		7631-86-9	1.85		0.000498	
		1303-86-2	0.45	Plating1	0.000044	
		7440-02-0	2.12		0.000011	
		7440-31-5	5.76	Plating2	0.000051	
					0.000138	
Capacitor2	BaTiO3 type Titanium dioxide Misc Ni Cu Silicon dioxide diboron trioxide; boric oxide Ni Sn	1304-28-5	31.67	Ceramic	<b>0.009200</b>	<b>0.078%</b>
		13463-67-7	15.83		0.002914	
		-	5.28	Inner Electrode	0.001456	
		7440-02-0	26.67		0.000486	
		7440-50-8	15.10	Outer Electrode	0.002454	
		7631-86-9	1.34		0.001389	
		1303-86-2	0.33	Plating1	0.000123	
		7440-02-0	1.00		0.000030	
		7440-31-5	2.78	Plating2	0.000092	
					0.000256	
Capacitor3	BaTiO3 type Titanium dioxide Misc Ni Cu Silicon dioxide diboron trioxide; boric oxide Ni Sn	1304-28-5	37.46	Ceramic	<b>0.021600</b>	<b>0.183%</b>
		13463-67-7	18.73		0.008091	
		-	6.24	Inner Electrode	0.004046	
		7440-02-0	17.95		0.001348	
		7440-50-8	15.88	Outer Electrode	0.003877	
		7631-86-9	1.41		0.003430	
		1303-86-2	0.35	Plating1	0.000305	
		7440-02-0	0.54		0.000076	
		7440-31-5	1.44	Plating2	0.000117	
					0.000311	
Capacitor4	BaTiO3 type Titanium dioxide Misc Ni Indium(III) oxide Tin dioxide Frits Nickel Cu Silicon dioxide diboron trioxide; boric oxide Ni Sn	1304-28-5	37.01	Ceramic	<b>0.003800</b>	<b>0.032%</b>
		13463-67-7	18.51		0.001406	
		-	6.17	Inner Electrode	0.000703	
		7440-02-0	4.90		0.000234	
		1312-43-2	9.15	Outer Electrode	0.000186	
		18282-10-5	1.83		0.000348	
		65997-18-4	5.49	Plating1	0.000070	
		7440-02-0	1.83		0.000209	
		7440-50-8	12.05	Plating2	0.000070	
		7631-86-9	0.27		0.000458	
1303-86-2	1.07		0.000010			
7440-02-0	0.49		0.000041			
7440-31-5	1.23		0.000019			
			0.000047			
Heat sink	Cu Ni	7440-50-8 7440-02-0	98.35 1.65	Main material Main material	<b>7.427400</b>	<b>62.988%</b>
					7.304848 0.122552	
Heat sink adhesive	Aluminium Oxide Al2O3 Dimethyl siloxane, dimethylvinyl-terminated	- 68083-19-2	80.00 20.00	Main material Main material	<b>0.120000</b>	<b>1.018%</b>
					0.096000 0.024000	
Solder ball	Sn Ag Cu	7440-31-5 7440-22-4 7440-50-8	96.50 3.00 0.50	Main material Main material Main material	<b>0.751829</b>	<b>6.376%</b>
					0.725515 0.022555 0.003759	
Substrate	Consigned				2.997057	<b>25.417%</b>
					2.997057	

**Revision History**

Date	Version	Description of Revisions
01/22/2016	1	Initial Xilinx release.

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